CLAIMS

What is Claimed is:

1. An audio sound quality enhancer comprising at least one solid-state component in an audio signal path; and at least one heat source configured to heat said at least one solid-state component.

2. The audio sound quality enhancer of Claim 1 wherein said at least one solid-state component in said audio signal path is heated to a junction temperature of at least 60°C.

3. The audio sound quality enhancer of Claim 1 wherein said at least one solid-state component in said audio signal path is heated to a junction temperature range of at least 80°C.

4. The audio sound quality enhancer of Claim 1 wherein said at least one solid-state component in said audio signal path is heated to a junction temperature range of between approximately 80°C and approximately 100°C.

5. The audio sound quality enhancer of Claim 1 wherein said at least one solid-state component in said audio signal path is heated to a junction temperature of at least 100°C.

6. The audio sound quality enhancer of Claim 1 wherein said at least one solid-state component in said audio signal path is heated to a junction temperature of at least 125°C.

7. The audio sound quality enhancer of Claim 1 wherein said at least one solid-state component in said audio signal path is heated to a junction temperature of at least 150°C.

8. The audio sound quality enhancer of Claim 1 wherein said at least one solid-state component in said audio signal path is heated to a junction temperature of at least 175°C.

9. The audio sound quality enhancer of Claim 1 wherein said at least one solid-state component is mounted on a circuit board, and said at least one heat source is associated with said circuit board.

10. The audio sound quality enhancer of Claim 9 wherein said at least one heat source is adjacent to said circuit board and positioned to heat said at least one solid-state component.

11. The audio sound quality enhancer of Claim 9 wherein said heat source is mounted on said circuit board and positioned to heat said at least one solid-state component.

12. The audio sound quality enhancer of Claim 1 wherein said at least one solid-state component comprises;

(a) a differential amplifier;

(b) an output driver; and

(c) an output device.

13. The audio sound quality enhancer of Claim 12 wherein said differential amplifier, said output driver, and said output device are selectively positioned on said circuit board such that they are proximate to said at least one heat source.

14. A method for generating audio sound comprising:

(a) providing an audio circuit having at least one solid-state component therein; and

(b) heating said at least one solid-state component to at least 60°C.

15. The method of claim 14, wherein said heating of said at least one solid-state component is carried out to at least 80°C.

16. The method of claim 15, wherein said heating of said at least one solid-state component is carried out to at least 100°C.

17. The method of claim 15, wherein said heating of said at least one solid-state component is carried out to at least 125°C.

18. The method of claim 15, wherein said heating of said at least one solid-state component is carried out to at least 150°C.

19. The method of claim 15, wherein said heating of said at least one solid-state component is carried out to at least 175°C.

20. The method of claim 14, further comprising monitoring temperature of said at least one solid-state component.

21. The method of claim 20, further comprising adjusting said heating of said heating of at least one solid-state component when said temperature of said solid-state component falls below 60°C.